Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Title - Representative Phone - Contact* Phone - Contact* Product-Env-Stewards@onsemi.com Phone - Representative* Email - Contact* Product-Env-Stewards@onsemi.com Phone - Representative* Phone - Representative* Product-Env-Stewards Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
Company name* Company unique ID Unique ID Authority Response Date* 2023-06-08 Contact Name Title - Contact Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards NA Nanufacturing Site Weight* UOM Unit NCP12700BDNR2G Current Mode PWM Controller NA NCP12700BDNR2G Current Mode PWM Controller Product-Env-Stewards NA NCP12700BDNR2G Current Mode PWM Controller NA NCP12700BDNR2G NCP12700BDNR2G NCP12700BDNR2G Current Mode PWM Controller NA NCP12700BDNR2G NCP12700BD	752-21.1											als and Mf	g Informat	ion		
Inter Name Inter Name Inter Contact Name Inter Contact Name Inter Contact Inter Contac	upplier Informa	ation						·								
Product Env-Stewards	Company name* Company unique ID				ique ID		Unique ID Authority					Response Date*				
Product-Env-Stewards	nsemi								20				2023-06-08			
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Reflective Date Requester Item Number Reflective Date Reflective Date Representative* Requester Item Number Reflective Date Requester Item Number	Contact Name			Title - Contact			1	Phone - Contact*				Email - Contact*				
Product Envi-Stewards Requester Item Number Mfr Item Nu	Product-Env-Stewar	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	uthorized Represen	Title - Representative			I	Phone - Representative*			Email - Representative*							
NCP12700BDNR2G Current Mode PWM Controller 2023-06-08 MY1 25.27 mg Each	Product-Env-Stewar	rds	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	r Item Number	Mfr Item Number Mf		Mfr Item Name			Effective Date	Version Manufacturing Site		V	Veight*	UOM	Unit Type		
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Comments			NCP1270	00BDNR2G	Current Mode PWN	M Controller		2023-06-08		N	МҮ1	2	5.27	mg	Each	
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3				arminal Paga	Alloy	STD 020 MSI	Dating	Dook Prog	ans Pady T	Comporative	May Time at Peak	Tamparatu	ro Numi	har of Paflaw Cya	los	
Comments	2 2			2			2 Kanng									
	•	(Sii) - aimeaieu		O Alloy	1			200		Ic	30	second	15 3			
ver 1 - maximum time at peak temperature during soldering is 10-30 seconds		mo at neak temperatura	duning col	doring is 10-2	10 seconds											
or more information regarding material composition please refer to page 3																

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.66	mg	Supplier	Silicon (Si)	7440-21-3		1.66	mg
Die Attach	0.18	mg	Supplier	Silver (Ag)	7440-22-4		0.135	mg
			Supplier	Epoxy resins	129915-35-1		0.045	mg
Lead Frame	10.12		Supplier	Magnesium (Mg)	7439-95-4		0.0152	mg
			Supplier	Silicon (Si)	7440-21-3		0.0658	mg
			В	Nickel (Ni)	7440-02-0		0.3036	mg
			Supplier	Copper (Cu)	7440-50-8		9.7354	mg
Mold Compound-Black	12.98	mg		Epoxy Phenol Resin	proprietary data		1.3629	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.6171	mg
Plating	0.17	mg	Supplier	Palladium (Pd)	7440-05-3		0.0106	mg
			В	Nickel (Ni)	7440-02-0		0.1576	mg
			Supplier	Gold (Au)	7440-57-5		0.0018	mg
Wire Bond - Au	0.16	mg	Supplier	Gold (Au)	7440-57-5		0.16	mg